Yuji Kasashima

List of Publications by Year
in descending order

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18	143	1163117	1199594
papers	citations	8 h-index	12 g-index

18	18	18	62
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Instantaneous Generation of Many Flaked Particles by Impulsive Force of Electric Field Stress Acting on Inner Wall of Mass-Production Plasma Etching Equipment. Japanese Journal of Applied Physics, 2013, 52, 066201.	1.5	28
2	Transport of a helicon plasma by a convergent magnetic field for high speed and compact plasma etching. Journal Physics D: Applied Physics, 2014, 47, 425201.	2.8	14
3	Detection of Micro-Arc Discharge Using ESC Wafer Stage With Built-In AE Sensor. IEEE Transactions on Semiconductor Manufacturing, 2013, 26, 350-354.	1.7	12
4	Many flaked particles caused by impulsive force of electric field stress and effect of electrostriction stress in mass-production plasma etching equipment. Japanese Journal of Applied Physics, 2014, 53, 040301.	1.5	12
5	Numerous flaked particles instantaneously generated by micro-arc discharge in mass-production plasma etching equipment. Japanese Journal of Applied Physics, 2015, 54, 01AE02.	1.5	11
6	Note: Practical monitoring system using characteristic impedance measurement during plasma processing. Review of Scientific Instruments, 2014, 85, 026103.	1.3	10
7	Impulsive force phenomenon of electric field stress causing serious particle contamination in plasma etching equipment. Japanese Journal of Applied Physics, 2014, 53, 110308.	1.5	8
8	Monitoring of inner wall condition in mass-production plasma etching process using a load impedance monitoring system. Japanese Journal of Applied Physics, 2015, 54, 060301.	1.5	8
9	Investigation of the relationship between plasma etching characteristics and microstructures of alumina ceramics for chamber parts. Japanese Journal of Applied Physics, 2019, 58, 041001.	1.5	8
10	Real-time characteristic impedance monitoring for end-point and anomaly detection in the plasma etching process. Japanese Journal of Applied Physics, 2014, 53, 03DC03.	1.5	7
11	Detection of microarc discharge using a high-speed load impedance monitoring system. Applied Physics Express, 2014, 7, 096102.	2.4	6
12	Development and evaluation of magnesium oxide-based ceramics for chamber parts in mass-production plasma etching equipment. Japanese Journal of Applied Physics, 2017, 56, 06HC01.	1.5	6
13	In-situ detection method for wafer movement and micro-arc discharge around a wafer in plasma etching process using electrostatic chuck wafer stage with built-in acoustic emission sensor. Japanese Journal of Applied Physics, 2014, 53, 03DC04.	1.5	4
14	Decrease in Particles by Substituting Conductive Magnesium-Oxide Based Ceramics for Conventional Electrode Materials Used in Process Chamber of Plasma Etching. IEEE Transactions on Semiconductor Manufacturing, 2021, 34, 224-226.	1.7	4
15	Development of a novel plasma probe for the investigation and control of plasmaâ€enhanced chemical vapor deposition coating processes. Plasma Processes and Polymers, 2020, 17, 2000077.	3.0	3
16	Easy-to-use detection method for micro-arc discharge in plasma etching equipment by measuring current flowing to ground. Japanese Journal of Applied Physics, 2018, 57, 098002.	1.5	2
17	Feasibility study of monitoring of plasma etching chamber conditions using superimposed high-frequency signals on rf power transmission line. Review of Scientific Instruments, 2015, 86, 105107.	1.3	0
18	Feasibility study of detection of dielectric breakdown of gate oxide film by using acoustic emission method. Japanese Journal of Applied Physics, 2016, 55, 128001.	1.5	0